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Foundations of
**Materials Science
and Engineering**

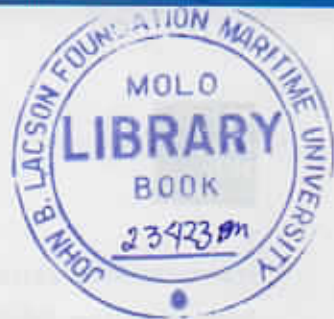
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Foundations of Materials Science and Engineering

Sixth Edition

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